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(54) Title: CONTACT MEMBER, CHUCK, AND ELECTROPLATING DEVICE

(54) 发明名称: 接触件、夹盘及电镀设备

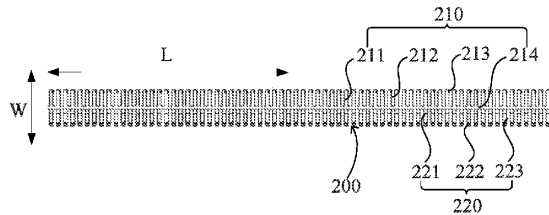


图 4

(57) Abstract: The present invention relates to the technical field of semiconductor electroplating, and provides a contact member, a chuck, and an electroplating device. The contact member extends in a straight line and comprises a mounting base body and a contact base body. The mounting base body comprises a plurality of mounting parts that are arranged at intervals, and the plurality of mounting parts are distributed in the length direction of the mounting base body. Adjacent mounting parts are separated by means of a first hollow area, and each mounting part is provided with a guide portion protruding from the mounting base body. The contact base body is provided with a plurality of second hollow areas distributed at intervals in the length direction thereof, and the contact base body is connected to the mounting base body so as to be used for contacting a substrate. The contact member provided by the present invention has a higher material utilization rate and generates less waste. The output rate of the contact member is higher, and the processing costs are lower. In addition, the contact member has good bending performance, and the contact member can be more easily bent into a ring for use from a state in which the contact member extends in a straight line.

(57) 摘要: 本发明提供了一种接触件、夹盘及电镀设备, 涉及半导体电镀技术领域, 接触件沿直线延伸, 包括安装基体和接触基体, 安装基体包括多个间隔设置的安装部, 多个安装部沿安装基体的长度方向分布, 相邻安装部之间通过第一镂空区域分隔开, 每一安装部上设置有凸出于所述安装基体的引导部, 接触基体设置有多个沿所述长度方向间隔分布的第二镂空区域, 接触基体与安装基体连接, 用于与基板接触。本发明提供的接触件, 材料利用率更高, 产生的废料更少, 接触件的产出率更高, 加工成本更低, 并且接触件具备良好的弯曲性能, 接触件可以由沿直线延伸的状态更容易被弯曲成环形进行使用。

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